HALOGEN

FREE

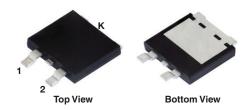


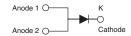
Vishay General Semiconductor

# TMBS® (Trench MOS Barrier Schottky) Rectifier for PV Solar Cell Bypass Protection

Ultra Low  $V_F = 0.26 \text{ V}$  at  $I_F = 5 \text{ A}$ 

## eSMP<sup>®</sup> Series SMPD (TO-263AC)





#### **LINKS TO ADDITIONAL RESOURCES**



PRIMARY CHARACTERISTICS				
I <sub>F(AV)</sub>	40 A			
$V_{RRM}$	45 V			
I <sub>FSM</sub>	240 A			
$V_F$ at $I_F = 40$ A $(T_A = 125  ^{\circ}C)$	0.53 V			
T <sub>OP</sub> max. (AC model)	150 °C			
T <sub>J</sub> max. (DC forward current)	200 °C			
Package	SMPD (TO-263AC)			
Circuit configuration	Single			

#### **FEATURES**

- Trench MOS Schottky technology
- Very low profile typical height of 1.7 mm
- · Ideal for automated placement
- Low forward voltage drop, low power losses
- High efficiency operation
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- Material categorization: for definitions of compliance please see <a href="https://www.vishay.com/doc?99912">www.vishay.com/doc?99912</a>

### **TYPICAL APPLICATIONS**

For use in solar cell junction box as a bypass diode for protection, using DC forward current without reverse bias.

## **MECHANICAL DATA**

Case: SMPD (TO-263AC)

Molding compound meets UL 94 V-0 flammability rating Base P/N-M3 - halogen-free, RoHS-compliant, and commercial grade

Terminals: Matte tin plated leads, solderable per

J-STD-002 and JESD 22-B102

M3 suffix meets JESD 201 class 2 whisker test

Polarity: As marked

MAXIMUM RATINGS (T <sub>A</sub> = 25 °C unless otherwise noted)					
PARAMETER	SYMBOL	V40DL45BP	UNIT		
Maximum repetitive peak reverse voltage	V <sub>RRM</sub>	45	V		
Maximum DC forward current (fig. 1)	I <sub>F(DC)</sub> (1)	40	Α		
Peak forward surge current 10 ms single half sine-wave superimposed on rated load	I <sub>FSM</sub>	240	А		
Operating junction temperature range (AC model)	T <sub>OP</sub>	-40 to +150	°C		
Junction temperature in DC forward current without reverse bias, $t = \le 1 \text{ h}$	T <sub>J</sub> <sup>(2)</sup>	≤ 200	°C		

#### Note

- (1) With heatsink
- (2) Meets the requirements of IEC 61215 ed.2 bypass diode thermal test



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<b>ELECTRICAL CHARACTERISTICS</b> (T <sub>A</sub> = 25 °C unless otherwise noted)						
PARAMETER	TEST CONDITIONS		SYMBOL	TYP.	MAX.	UNIT
Instantaneous forward voltage	I <sub>F</sub> = 5 A	T <sub>A</sub> = 25 °C	T <sub>A</sub> = 25 °C V <sub>F</sub> <sup>(1)</sup> T <sub>A</sub> = 125 °C	0.38	-	. V
	I <sub>F</sub> = 20 A			0.47	-	
	I <sub>F</sub> = 40 A			0.58	0.66	
	I <sub>F</sub> = 5 A	T <sub>A</sub> = 125 °C		0.26	-	
	I <sub>F</sub> = 20 A			0.38	-	
	I <sub>F</sub> = 40 A			0.53	0.61	
Reverse current	V - 45 V	T <sub>A</sub> = 25 °C	I <sub>R</sub> <sup>(2)</sup>	-	5	- mA
	v <sub>R</sub> = 45 v	$V_R = 45 \text{ V}$ $T_A = 125 \text{ °C}$		36	125	

#### **Notes**

(1) Pulse test: 300 µs pulse width, 1 % duty cycle

(2) Pulse test: Pulse width ≤ 5 ms

THERMAL CHARACTERISTICS (T <sub>A</sub> = 25 °C unless otherwise noted)				
PARAMETER	SYMBOL V40DL45BP			
Typical thermal resistance	$R_{ heta JC}$	0.9	°C/W	
	R <sub>0JA</sub> (1)(2)	45	C/VV	

#### Notes

 $^{(1)}$  The heat generated must be less than the thermal conductivity from junction-to-ambient:  $dP_D/dT_J < 1/R_{\theta JA}$ 

(2) Free air, without heatsink

ORDERING INFORMATION (Example)					
PACKAGE	PREFERRED P/N	UNIT WEIGHT (g)	PACKAGE CODE	BASE QUANTITY	DELIVERY MODE
SMPD (TO-263AC)	V40DL45BP-M3/I	0.55	1	2000/reel	13" diameter plastic tape and reel

## **RATINGS AND CHARACTERISTICS CURVES** ( $T_A = 25$ °C unless otherwise noted)

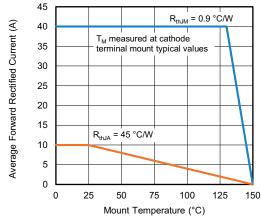


Fig. 1 - Forward Current Derating Curve

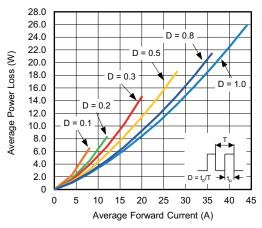


Fig. 2 - Forward Power Loss Characteristics



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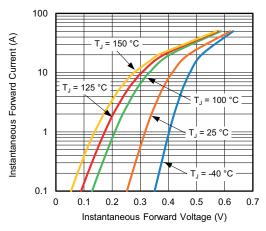


Fig. 3 - Typical Instantaneous Forward Characteristics

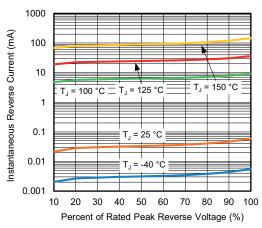


Fig. 4 - Typical Reverse Characteristics

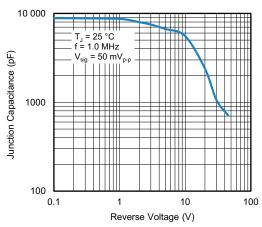


Fig. 5 - Typical Junction Capacitance

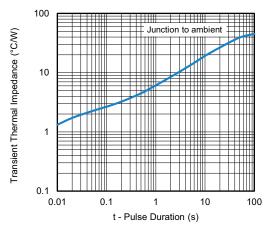


Fig. 6 - Typical Transient Thermal Impedance

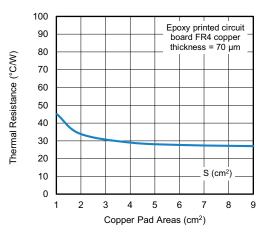
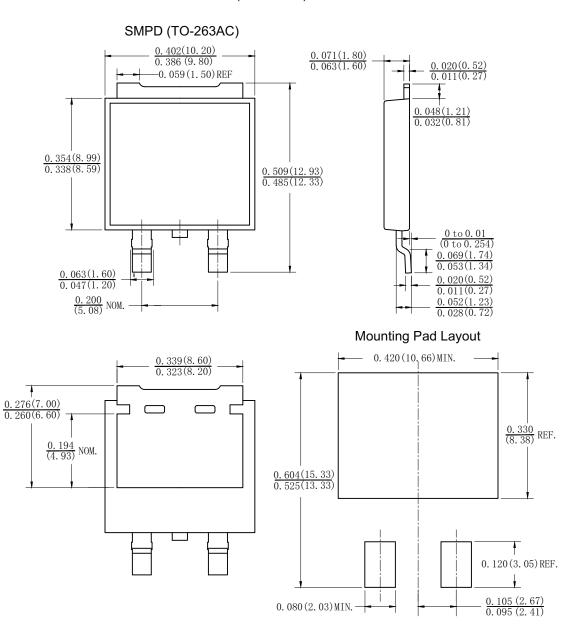


Fig. 7 - Thermal Resistance Junction-to-Ambient vs. Copper Pad Areas



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## **PACKAGE OUTLINE DIMENSIONS** in inches (millimeters)





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